

Global Semiconductor Wafer Back Grinding Equipment Supply, Demand and Key Producers, 2026-2032

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Abstracts

The global Semiconductor Wafer Back Grinding Equipment market size is expected to reach \$ 2428 million by 2032, rising at a market growth of 6.1% CAGR during the forecast period (2026-2032).

Semiconductor Wafer Back Grinding Equipment refers to precision semiconductor manufacturing equipment used to thin wafers from the backside after front-end processing. The process involves mechanical grinding, polishing, and stress relief techniques to reduce wafer thickness and enable ultra-thin wafers required for advanced packaging and high-performance semiconductor devices. It is widely used in wafer-level packaging, 3D IC integration, memory devices, image sensors, power semiconductors, and advanced logic chips. The equipment typically includes grinding wheels, wafer chuck systems, cooling and slurry systems, thickness measurement modules, and automated control units. The industrial chain of Semiconductor Wafer Back Grinding Equipment includes upstream components such as diamond grinding wheels, abrasives, polishing pads, wafer chucks, motion control systems, sensors, cooling and filtration systems, and control software. The midstream consists of equipment design, wafer thinning process development, stress optimization, surface damage control, automation integration, metrology calibration, system installation, and maintenance services. Downstream applications include semiconductor fabs, advanced packaging facilities, memory manufacturers, image sensor producers, power semiconductor companies, and 3D IC integration processes. The industry requires ultra-high precision, wafer uniformity, surface integrity control, and low defect density. In 2025, global Semiconductor Wafer Back Grinding Equipment production reached approximately 3,714 units, with an average global market price of around US\$420,000 per unit. The gross profit margin of major companies in the industry is between 30% ?

50%. In 2025, the global production capacity of Semiconductor Wafer Back Grinding Equipment was approximately 4,952 units.

The Semiconductor Wafer Back Grinding Equipment market is driven by increasing demand for ultra-thin wafers in advanced semiconductor packaging and device miniaturization. As chip architectures evolve toward higher integration density, 3D IC structures, and heterogeneous integration, wafer thinning has become a critical process step. Back grinding improves electrical performance, reduces device thickness, and enhances thermal management. The market is strongly supported by applications in memory devices, image sensors, power semiconductors, and advanced logic chips. Key technology trends include ultra-precision grinding, low-stress thinning, in-situ metrology, and fully automated wafer handling systems. However, challenges such as wafer cracking, surface damage control, and yield stability remain. Overall, the market is expected to grow steadily with the expansion of advanced packaging and semiconductor scaling technologies.

This report studies the global Semiconductor Wafer Back Grinding Equipment production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for Semiconductor Wafer Back Grinding Equipment and provides market size (US\$ million) and Year-over-Year (YoY) Growth, considering 2025 as the base year. This report explores demand trends and competition, as well as details the characteristics of Semiconductor Wafer Back Grinding Equipment that contribute to its increasing demand across many markets.

Highlights and key features of the study

Global Semiconductor Wafer Back Grinding Equipment total production and demand, 2021-2032, (Units)

Global Semiconductor Wafer Back Grinding Equipment total production value, 2021-2032, (USD Million)

Global Semiconductor Wafer Back Grinding Equipment production by region & country, production, value, CAGR, 2021-2032, (USD Million) & (Units), (based on production site)

Global Semiconductor Wafer Back Grinding Equipment consumption by region & country, CAGR, 2021-2032 & (Units)

U.S. VS China: Semiconductor Wafer Back Grinding Equipment domestic production, consumption, key domestic manufacturers and share

Global Semiconductor Wafer Back Grinding Equipment production by manufacturer,

production, price, value and market share 2021-2026, (USD Million) & (Units)
Global Semiconductor Wafer Back Grinding Equipment production by Type, production, value, CAGR, 2021-2032, (USD Million) & (Units)
Global Semiconductor Wafer Back Grinding Equipment production by Application, production, value, CAGR, 2021-2032, (USD Million) & (Units)

This report profiles key players in the global Semiconductor Wafer Back Grinding Equipment market based on the following parameters - company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include DISCO Corporation, ACCRETECH Tokyo Seimitsu Co., Ltd., Okamoto Machine Tool Works, Ltd., Revasum, Inc., Komatsu NTC Ltd., JTEKT Machinery Americas Corporation, Lapmaster Wolters GmbH, G&N Genauigkeits Maschinenbau N?rnberg GmbH, Engis Corporation, Logitech Ltd., etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World Semiconductor Wafer Back Grinding Equipment market

Detailed Segmentation:

Each section contains quantitative market data including market by value (US\$ Millions), volume (production, consumption) & (Units) and average price (K US\$/Unit) by manufacturer, by Type, and by Application. Data is given for the years 2021-2032 by year with 2025 as the base year, 2026 as the estimate year, and 2027-2032 as the forecast year.

Global Semiconductor Wafer Back Grinding Equipment Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

Global Semiconductor Wafer Back Grinding Equipment Market, Segmentation by Type:

Coarse Back Grinding Equipment

Fine Back Grinding Equipment

Ultra-fine Back Grinding Equipment

Global Semiconductor Wafer Back Grinding Equipment Market, Segmentation by Equipment Automation Level:

Manual Wafer Back Grinding Equipment

Semi-Automatic Wafer Back Grinding Equipment

Fully Automatic Wafer Back Grinding Equipment

Global Semiconductor Wafer Back Grinding Equipment Market, Segmentation by Wafer Diameter:

Up to 200 mm Wafer Diameter

Above 200 mm to 300 mm Wafer Diameter

Above 300 mm Wafer Diameter

Global Semiconductor Wafer Back Grinding Equipment Market, Segmentation by

Application:

Advanced Packaging Wafer Thinning

Power Semiconductor Wafer Thinning

MEMS and Sensor Wafer Thinning

Compound Semiconductor Wafer Thinning

Companies Profiled:

DISCO Corporation

ACCRETECH Tokyo Seimitsu Co., Ltd.

Okamoto Machine Tool Works, Ltd.

Revasum, Inc.

Komatsu NTC Ltd.

JTEKT Machinery Americas Corporation

Lapmaster Wolters GmbH

G&N Genauigkeits Maschinenbau Nürnberg GmbH

Engis Corporation

Logitech Ltd.

Beijing CETC Electronic Equipment Group Co., Ltd.

Hwatsing Technology Co., Ltd.

Key Questions Answered:

1. How big is the global Semiconductor Wafer Back Grinding Equipment market?
2. What is the demand of the global Semiconductor Wafer Back Grinding Equipment market?
3. What is the year over year growth of the global Semiconductor Wafer Back Grinding Equipment market?
4. What is the production and production value of the global Semiconductor Wafer Back Grinding Equipment market?
5. Who are the key producers in the global Semiconductor Wafer Back Grinding Equipment market?
6. What are the growth factors driving the market demand?

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